



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC059N04LS6		<b>Issued</b>		4. July 2019		
<b>MA#</b>		MA005209726						
<b>Package</b>		PG-TDSON-8-25		<b>Weight*</b>		113.19 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.242	0.21	0.21	2138	2138
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		137	
	non noble metal	iron	7439-89-6	0.052	0.05		458	
wire	non noble metal	copper	7440-50-8	51.740	45.71	45.77	457101	457696
	noble metal	gold	7440-57-5	0.048	0.04	0.04	420	420
encapsulation	organic material	carbon black	1333-86-4	0.084	0.07		741	
	plastics	epoxy resin	-	6.629	5.86		58565	
leadfinish	inorganic material	silicondioxide	60676-86-0	35.243	31.14	37.07	311358	370664
	non noble metal	tin	7440-31-5	1.392	1.23	1.23	12294	12294
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1712	1712
solder	non noble metal	tin	7440-31-5	0.008	0.01		71	
	noble metal	silver	7440-22-4	0.010	0.01		88	
heat sink clip	non noble metal	lead	7439-92-1	0.382	0.34	0.36	3372	3531
	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
*deviation	non noble metal	iron	7439-89-6	0.017	0.02		152	
	non noble metal	copper	7440-50-8	17.131	15.13	15.15	151348	151545
Sum in total:						100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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